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In cooperation with:

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Venue: Pullman Hotel in Eindhoven



Conference Banquet Dinner at Philips Light Museum



The EMLC 2015 International Program Committee

Conference Chairs Uwe Behringer,
UBC Microelectronics,
Ammerbuch, Germany
Jo Finders, ASML, Veldhoven,
Netherlands

Co-Conference Chairs Chris Gale, Applied Materials, Dresden,
Germany
Naoya Hayashi, DNP, Saitama, Japan

Program Chairs Daniel Sarlette, Infineon Technologies
GmbH, Dresden, Germany
Brid Connolly, Toppan Photomasks
GmbH, Dresden, Germany
Rolf Seltmann, Globalfoundries,
Dresden, Germany

Other Members

Michael Arnz, Carl Zeiss SMT AG, Oberkochen, Germany
Carola Blaesing, Carl Zeiss SMS GmbH, Jena, Germany
Parkson Chen, Taiwan Mask Corp., Hsinchu, Taiwan
Rik Jonckheere, IMEC, Leuven, Belgium
Barbara Lauche, Photonics MZD GmbH, Dresden, Germany
Bertrand Le Gratiet, STMicroelectronics, Crolles, Cedex, France
Harry Levinson, Globalfoundries, Santa Clara, CA, USA
Hans Löschner, IMS Nanofabrication AG, Vienna, Austria
Jan Hendrik Peters, Carl Zeiss SMS GmbH, Jena, Germany
Wilhelm Maurer, Infineon, Munich, Germany
Emmanuel Rausa, Plasma-Therm USA, St Petersburg, FL, USA
Klaus-Dieter Röth, KLA-Tencor MIE, Weilburg, Germany
Hella Scheer, University of Wuppertal, Germany
Thomas Scherübl, Carl Zeiss SMS GmbH, Jena, Germany
Ronald Schnabel, VDE/VDI-GMM, Frankfurt, Germany
Steffen Schulze, Mentor Graphics Corp. Wilsonville, OR, USA
Ines Stolberg, Vistec Electron Beam GmbH, Jena, Germany
Serge Tedesco, CEA-LETI, Grenoble, France
Jacques Waelpoel, ASML, Veldhoven, Netherlands
Guido Wenz, Wenz Consulting, Weil im Schoenbuch, Germany
Hermann Wolf, Photonics MZD GmbH, Dresden, Germany
Stefan Wurm, SEMATECH, Albany, NY, USA
Larry Zurbrick, Agilent Technologies, Santa Clara, CA, USA

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GMM

VDE/VDI-GESELLSCHAFT
MIKROELEKTRONIK, MIKROSYSTEM-
UND FEINWERKTECHNIK



Call for Papers

The 31st European Mask and Lithography Conference EMLC 2015

June 22 – 23, 2015
Pullman Hotel
Eindhoven, The Netherlands

www.EMLC2015.com



The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, SEMI-Europe, and SPIE, are pleased to announce the

31st European Mask and Lithography Conference, EMLC 2015

at the Pullman Hotel in Eindhoven, NL
June 22 - June 23, 2015

The focus of this 2-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users and their tool suppliers become acquainted with new developments and results.

Conference Schedule

The conference will start on Monday, June 22, 2015 at 09:00 AM with a Keynote Session. The conference will close on Tuesday, June 23, 2015, late afternoon. The Poster Session will be held on Monday evening followed by the Conference Banquet Dinner.

Technical Exhibition

On Monday and Tuesday (June 22nd and 23rd 2015) there will be a technical exhibition with booth space for about 20 exhibitors. Presentation tables and pin boards will be available. To be part of this Technical Exhibition, please return the **enclosed registration form** to the conference chairperson as soon as possible, since exhibition space is limited.

Conference Chairperson and Exhibition Organization

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Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including figures, diagrams, formatted text as Word-doc and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2015.com

There you will find a link to myspie.org

■ **Deadline for Abstracts: Monday, March 23rd 2015**

! **By submitting an abstract you agree to**

- Present your work in person at the conference and
- • Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **April 10th 2015**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript as early as possible but not later than the

■ **Deadline for Manuscripts: camera ready June 15th 2015**

Further information on the submission procedure can be found at www.emlc2015.com

All manuscripts will be subjected to a critical peer review before they are accepted for publication.

Please note that late submissions may not be published.

Manuscripts will be published by SPIE, also on the SPIE Digital Library. For layout information please follow the instructions provided at <http://spie.org/x14101.xml>

Conference Topics

Presentations are solicited for the following and related topics:

Mask Manufacturing

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies

- EUV Materials, Tools & Processes
- EUV Mask Infrastructure
- NIL
- Direct Write / Maskless Technologies

Mask and Lithography Equipment

- Mask Manufacturing

Semiconductors applied in Automotive

Semiconductors in MEMS Applications

Patterned Media